



HSA1300D

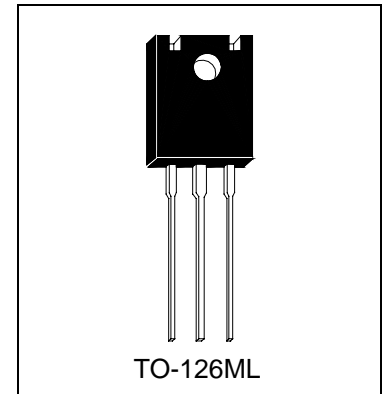
SILICON PNP EPITAXIAL TYPE

Description

- Strobe Flash Applications
- Medium Power Amplifier Applications

Features

- High DC Current Gain and Excellent hFE Linearity
- $hFE(1)=140-600$, ($V_{CE}=-1V$, $I_C=-0.5A$)
- $hFE(2)=60$ (Min.), 120 (Typ.), ($V_{CE}=-1V$, $I_C=-4A$)
- Low Saturation Voltage.
- $V_{CE(sat)}=-0.5V$ (Max.), ($I_C=-2A$, $I_E=-50mA$)



Absolute Maximum Ratings (Ta=25°C)

Characteristic		Symbol	Ratios	Unit
Collector-Base Voltage		VCBO	-20	V
Collector-Emitter Voltage		VCES	-20	V
		VCEO	-10	
Emitter-Base Voltage		VEBO	-6	V
Collector Current	DC	IC	-2	A
	Pulsed (Note1)	ICP	-5	
Base Current		IB	-2	A
Collector Power Dissipation		PC	1.5	W
Junction Temperature		Tj	150	°C
Storage Temperature Range		Tstg	-55~150	°C

Note 1: Pulse Width=10ms(Max.), Duty Cycle=30%(Max.)

Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Condition
V(BR)CEO	-10	-	-	V	IC=10mA, IB=0
V(BR)EBO	-6	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-100	nA	VCE=-20V, IE=0
IEBO	-	-	-100	nA	VBE=-6V, IC=0
*hFE(1) (Note 2)	140	-	600		VCE=-1V, IC=0.5A
*hFE(2)	60	120	-		VCE=-1V, IC=-4A
*VCE(sat)	-	-0.20	-0.50	V	IC=-2A, IB=-50mA
VBE	-	-0.83	-1.5	V	VCE=-1V, IC=-2A
fT	-	140	-	MHz	VCE=-1V, IC=-0.5A
Cob	-	50	-	pF	VCE=-10V, IE=0, f=1KHZ

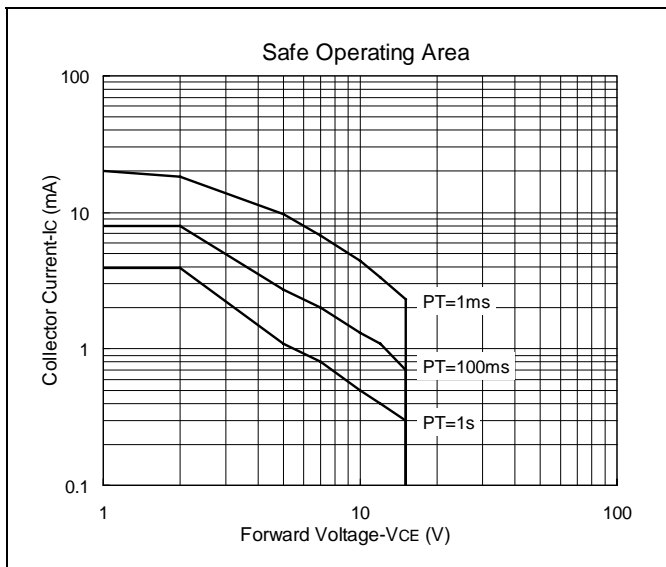
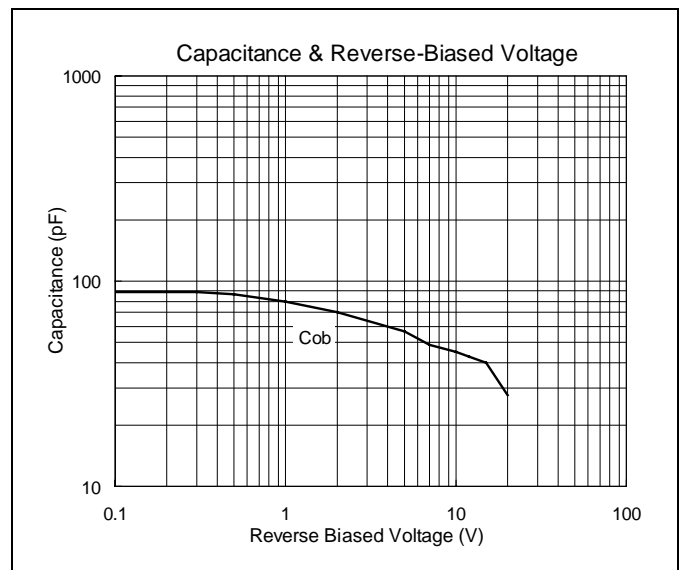
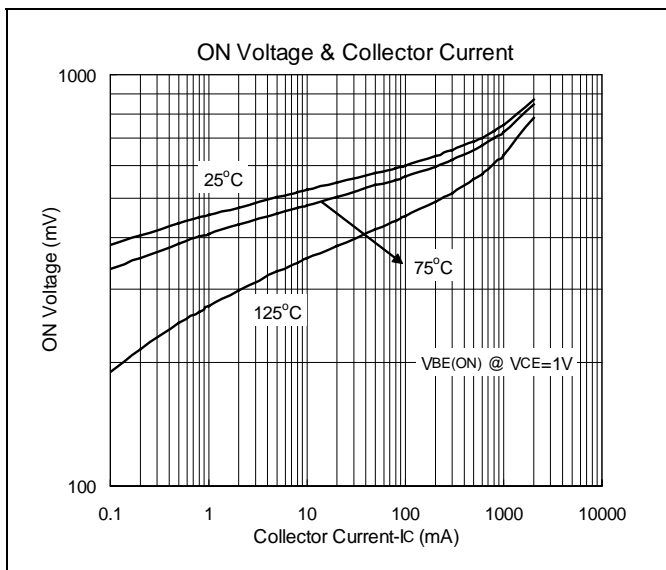
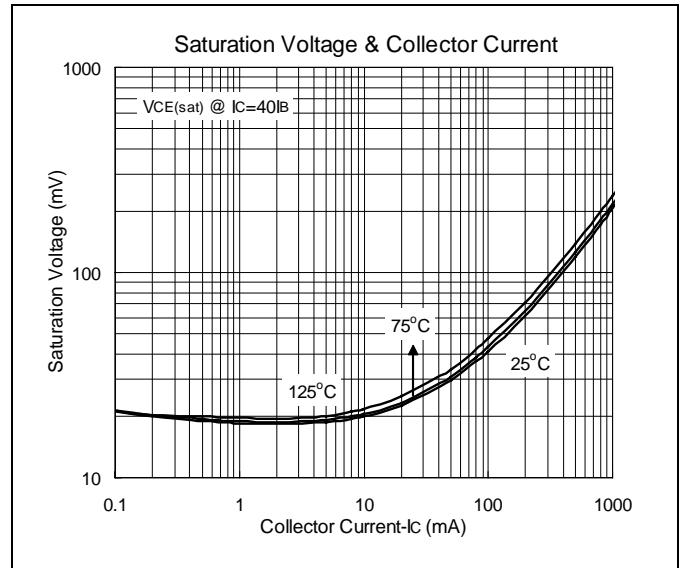
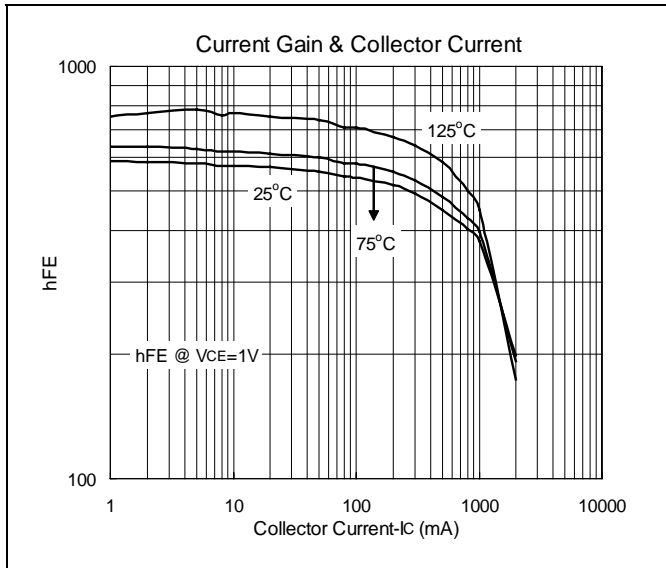
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Classifications of hFE

Rank	Y	GR	EL
hFE(1)	140-280	200-400	300-600

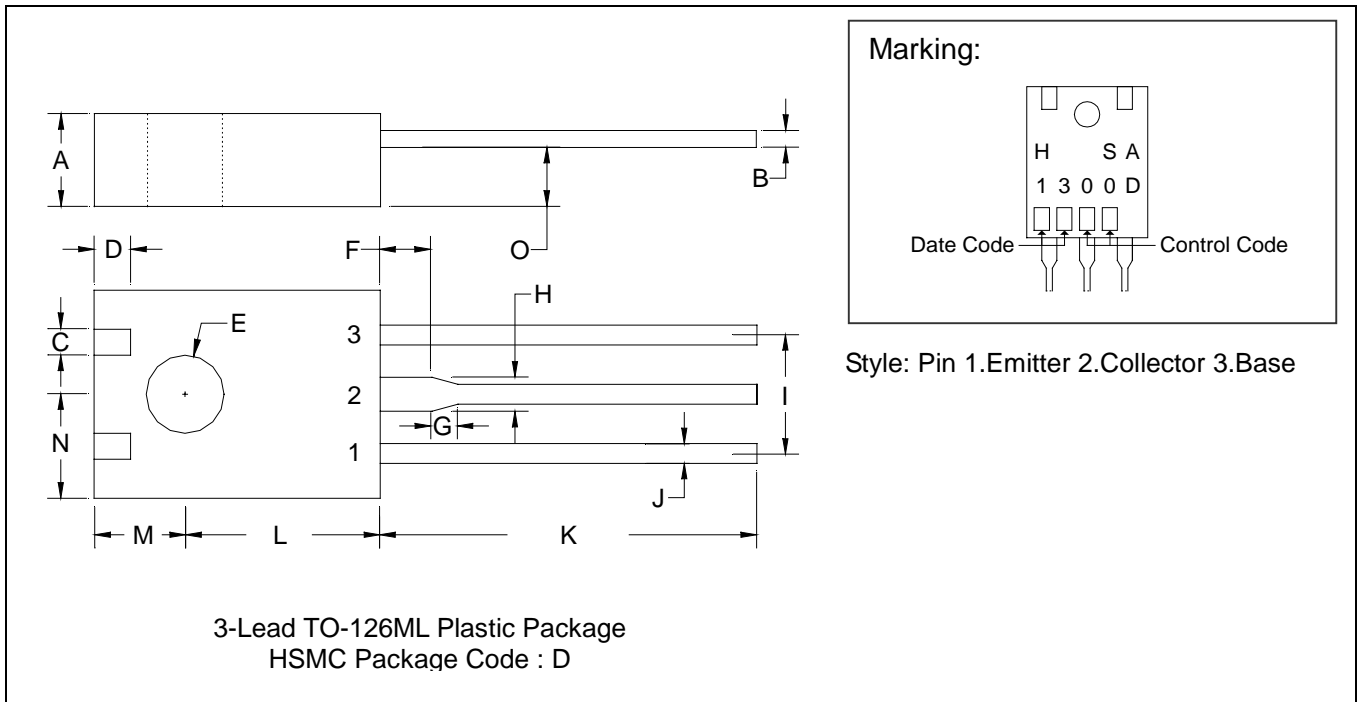


Characteristics Curve





TO-126ML Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes: 1. Dimension and tolerance based on our Spec. dated Mar. 6, 1995.
 2. Controlling dimension: millimeters.
 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931